

**METHOD AND STRUCTURE TO SUPPORT HEAT
SINK ARRANGEMENT ON CHIP CARRIER
PACKAGES**

ABSTRACT OF THE DISCLOSURE

A method and an arrangement for the supporting of the weight of a heat sink or heat-dissipating thermal structure, which is arranged on the surface of a chip carrier packages. More specifically, the arrangement and method are directed to relieving stresses generated by the weight of the heat sink in the solder balls between the chip carrier package and a printed circuit board (PCB) through a unique locking connection between the chip carrier package and the printed circuit board.